

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

1. (Original) A laminate of magnetic substrates comprising a high molecular compound layer and a magnetic metal thin plate, wherein metals partially contact one another between the thin plates and the volume resistivity defined in JIS H 0505 in a direction perpendicular to an adhesive surface of the laminate is from 0.1 to less than  $10^8 \Omega\text{cm}$ .

2. (Original) The laminate of magnetic substrates according to claim 1, wherein the high molecular compound layer covers not less than 50% of the area of an adhesive surface of the magnetic metal thin plate and the volume resistivity defined in JIS H 0505 in a direction perpendicular to the adhesive surface of the laminate is from  $1 \Omega\text{cm}$  to  $10^6 \Omega\text{cm}$ .

3. (Original) The laminate of magnetic substrates according to claim 1, wherein two or more kinds of magnetic metal thin plate are used as the magnetic metal thin plate constituting a magnetic substrate for use in the laminate of magnetic substrates.

4. (Original) The laminate of magnetic substrates according to claim 1, wherein the magnetic metal thin plate is made of at least two kinds of metals

selected from an amorphous metal, a nano crystal magnetic metal or a silicon steel sheet.

5. (Original) The laminate of magnetic substrates according to claim 3, wherein the magnetic metal thin plate is made of an amorphous metal and a silicon steel sheet.

6. (Original) A method of manufacturing the laminate of magnetic substrates of claim 1, wherein two or more sheets of the magnetic substrates comprising the high molecular compound layer and the magnetic metal thin plate are stacked and pressure of from 0.2 to 100 MPa is applied thereto such that the metals partially contact one another between the thin plates.

7. (Original) A method of manufacturing the laminate of magnetic substrates of claim 1 obtained by coating not less than 50% of the area of the magnetic metal thin plate with the high molecular compound and then drying, punching the magnetic metal thin plates obtained, stacking them and subjecting them to plastic deformation, and heating the resulting magnetic metal thin plates while applying pressure of from 0.2 to 100 MPa for an integrated lamination.

8. (Original) The method of manufacturing the laminate of magnetic substrates according to claim 7, wherein the method of subjecting to plastic deformation is a caulking process.

9. (Currently Amended) The laminate of magnetic substrates according to claim [[1 or]] 3, wherein the laminate of magnetic substrates is used for any of a transformer, an inductor and an antenna.

10. (Currently Amended) The laminate of magnetic substrates according to claim [[1 or]] 3, wherein the laminate of magnetic substrates is used for a magnetic core material of a stator or a rotor of a motor or a generator.

11. (New) The laminate of magnetic substrates according to claim 1, wherein the laminate of magnetic substrates is used for any of a transformer, an inductor and an antenna.

12. (New) The laminate of magnetic substrates according to claim 1, wherein the laminate of magnetic substrates is used for a magnetic core material of a stator or a rotor of a motor or a generator.